Product Change Notification

The information below reflects a change that is being implemented.

Notice Date: 11/02/2007

Product Category: Battery Management; Linear Devices; Mixed Signal Devices; Power Management; Supervisor; Thermal Management; dsPIC; CAN Communication; Infrared Communication; LIN Communication; Serial Communication; 24xxx; 25xxx; 93xxx; PIC10xxx; PIC12xxx; PIC16xxx; PIC17xxx; PIC18xxx; PIC24xxx; RFID; SDP

Notification Subject: CCB#764.01-764.04: QUALIFICATION OF G600 MOLD COMPOUND IN PDIP PACKAGES AT CEI AND NSEB

Notification Body:

All Microchip Catalog Part#s Affected For:
40L PDIP assembled at CEI (CCB# 764.01, for G600 Mold Compound)
8L PDIP assembled at NSEB (CCB# 764.02, for G600 Mold Compound)
18L PDIP assembled at NSEB (CCB# 764.03, for G600 Mold Compound)
28L PDIP assembled at NSEB (CCB# 764.04, for G600 Mold Compound)

Description of Change:
CHANGE IN BOM

Impacts to Data Sheet:
NONE

Reason for Change:
CONVERSION TO G600 MOLD COMPOUND

Estimated Change Implementation Date(s):
NOVEMBER 30, 2007

Markings to Distinguish Revised From Unrevised Devices:

(e.g.: Date Code, Device Marking, Ship Container Marking)

TRACEABILITY CODE